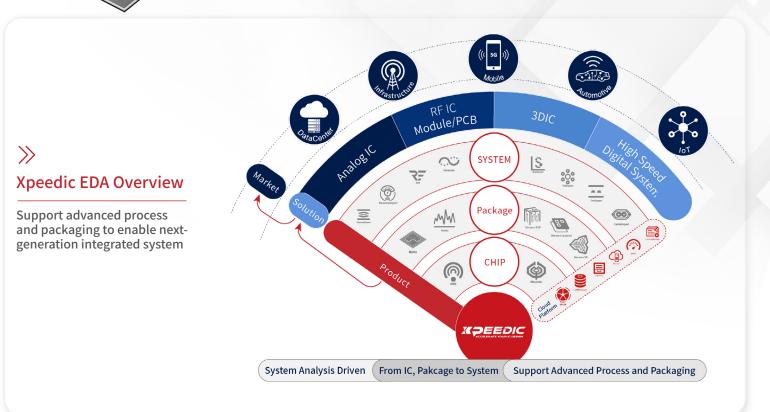
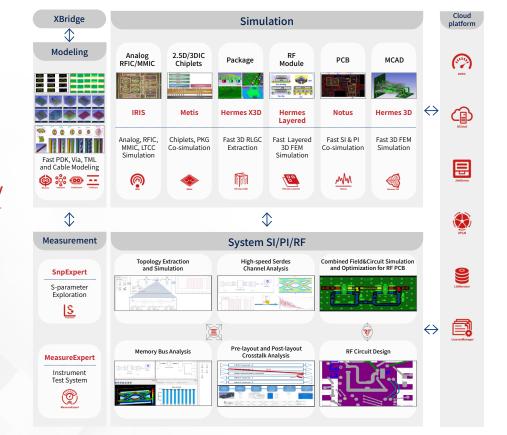


Xpeedic Simulation EDA for IC-Package-System





Xpeedic EDA Product Family

Modeling, Simulation, Analysis, Measurement, Cloud

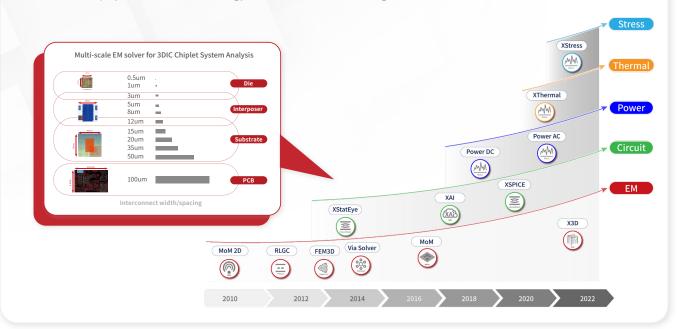


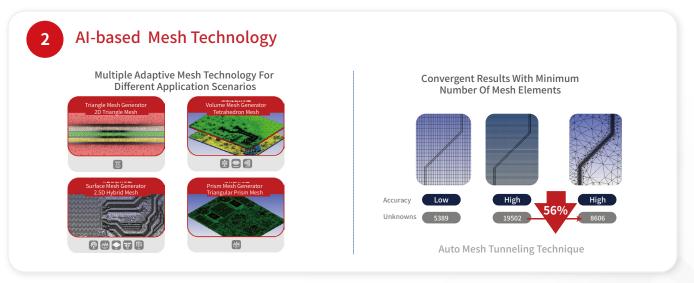
1

Xpeedic EDA Core Technologies

Industry Leading Solver Technology

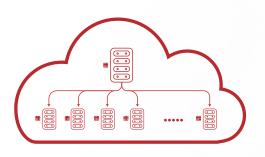
Multi physics solver technology from circuit, electromagnetic, thermal to stress simulation



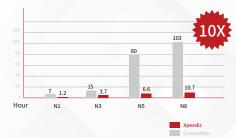


High Performance Distributed Parallel Computing Technology

Matrix-level Distributed Parallel Computing By MPI



Success Cases: Use Metis for Advanced Packaging Simulation Result: Metis delivers 10X simulation speed comparing to the other tools.



Xpeedic is a leading EDA provider to accelerate designs and simulations of next generation high-frequency, high-speed intelligent electronic products. Powered by its proprietary electromagnetic, circuit, and multi-physics solver technologies, Xpeedic is addressing challenges in designing IC in advanced nodes, 3D-IC with advanced packaging, high-speed digital, and RF systems for the markets including data center, automotive, communication, mobile, and IoT. For more information, please visit www.xpeedic.com.